



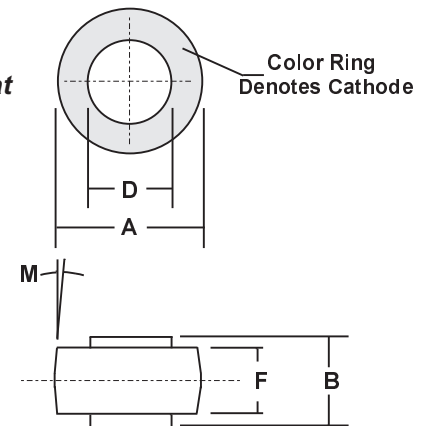
60 AMP BUTTON DIODES

Features

- Void Free Vacuum Die Soldering For Maximum Mechanical Strength and Heat Dissipation (Solder Voids: Typical $\leq 2\%$, Max. $\leq 10\%$ of Die Area)
- Biggest Effective Die Area for the 60 Amp Class of Button Diodes
- High Temperature Solder (Solidus 287°C , Liquidus 296°C) to Allow Higher Operating And Assembly Temperatures
- Copper Headers Are Silver Plated For Easy Soldering And Superior Solder Joints

Mechanical Specification

Die Size:
0.0220" Flat to Flat
Hex



Mechanical Data

- Case: Molded Epoxy (UL Flammability Rating 94V-O)
- Finish: All Metal Surfaces Are Silver Plated
- Soldering Temperature: 250°C maximum
- Mounting Position: Any
- Polarity: Color band denotes cathode
- Weight: 0.6 Ounces (1.8 Grams)

RoHS COMPLIANT

Dim	Millimeters		Inches	
	Min	Max	Min	Max
A	9.78	10.29	0.385	0.405
B	5.97	6.35	0.235	0.250
D	5.46	5.71	0.215	0.225
F	4.19	4.45	0.165	0.175
M	5° NOM		5° NOM	

Maximum Ratings & Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Parameter (Test Conditions)	Symbol	Ratings								Units
Series Number		BAR 6000	BAR 6001	BAR 6002	BAR 6004	BAR 6006	BAR 6008	BAR 6010		
Maximum DC Blocking Voltage	VRRM	50	100	200	400	600	800	1000	Volts	
Maximum RMS Voltage	VRWM									
Maximum Peak Recurrent Reverse Voltage	VDC									
Non-repetitive Peak Reverse Voltage (Half wave, single phase, 60 Hz peak)	VRSM	60	120	240	480	720	960	1200		
Average Forward Rectified Current @ Tc=125 °C	IO	60							Amps	
Peak Forward Surge Current (8.3mS single half sine wave superimposed on rated load)	IFSM	700								
Maximum Instantaneous Forward Voltage Drop at 60 Amp DC	VFM	1.1 (1.05 Typical)					1.15		Volts	
Maximum Average DC Reverse Current @ TA = 25 °C At Rated DC Blocking Voltage @ TA = 125 °C	IRM	1 50							µA	
Maximum Thermal Resistance, Junction to Case (Note 1)	RθJC	0.8							°C/W	
Junction Operating and Storage Temperature Range	TJ, TSTG	-65 to +175							°C	

Notes: 1) Single Side Cooled

BAR60